3.3V CMOS Static RAM 4 Meg (256K x 16-Bit)

IDT71V416S IDT71V416L

Features

- 256K x 16 advanced high-speed CMOS Static RAM
- ◆ JEDEC Center Power / GND pinout for reduced noise.
- Equal access and cycle times
 - Commercial and Industrial: 10/12/15ns
- One Chip Select plus one Output Enable pin
- Bidirectional data inputs and outputs directly LVTTL-compatible
- Low power consumption via chip deselect
- Upper and Lower Byte Enable Pins
- Single 3.3V power supply
- Available in 44-pin, 400 mil plastic SOJ package and a 44pin, 400 mil TSOP Type II package and a 48 ball grid array, 9mm x 9mm package.

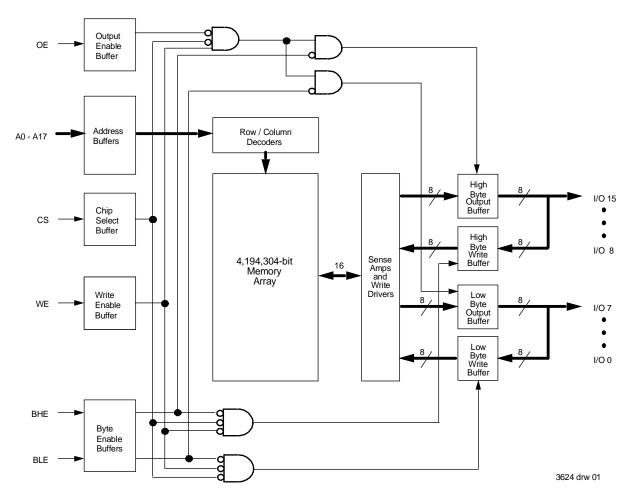
Description

The IDT71V416 is a 4,194,304-bit high-speed Static RAM organized as 256K x 16. It is fabricated using IDT's high-perfomance, high-reliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a cost-effective solution for high-speed memory needs.

The IDT71V416 has an output enable pin which operates as fast as 5ns, with address access times as fast as 10ns. All bidirectional inputs and outputs of the IDT71V416 are LVTTL-compatible and operation is from a single 3.3V supply. Fully static asynchronous circuitry is used, requiring no clocks or refresh for operation.

The IDT71V416 is packaged in a 44-pin, 400 mil Plastic SOJ and a 44-pin, 400 mil TSOP Type II package and a 48 ball grid array, 9mm x 9mmpackage.

Functional Block Diagram



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Pin Configurations - SOJ/TSOP

\bigcirc A0 1 44 A17 2 Α1 43 A16 Α2 3 42 A15 OE АЗ 4 41 BHE 5 40 A4 BLE 6 39 CS 1/0 0 7 I/O 15 38 I/O 1 [[] 8 37 I/O 14 I/O 13 I/O 2 L 9 36 I/O 3 I/O 12 10 35 SO44-1 VDD 11 34 Vss SO44-2 Vss 12 VDD 33 I/O 4 L 13 32 I/O 11 I/O 5 I/O 10 31 14 1/0 6 □ I/O 9 15 30 1/0 7 16 29 I/O 8 WE NC* 17 28 Α5 18 27 A14 A13 19 26 A6 A12 Α7 20 25 A11 **8**A 21 24 A10 22 23 A9

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Top View

Pin Descriptions

A0 - A17	Address Inputs	Input
CS	Chip Select	Input
WE	Write Enable	Input
ŌĒ	Output Enable	Input
BHE	High Byte Enable	Input
BLE	Low Byte Enable	Input
I/O0 - I/O15	Data Input/Output	I/O
VDD	3.3V Power	Pwr
Vss	Ground	Gnd

3624 tbl 01

Pin Configurations - 48 BGA

	1	2	3	4	5	6
Α	BLE	ŌĒ	Ao	A 1	A2	NC
В	I/O ₀	BHE	Аз	A 4	c s	V O8
С	I/O ₁	1/02	A 5	A 6	I/O ₁₀	VO9
D	Vss	I/O3	A 17	A 7	I/O ₁₁	VDD
Ε	Vdd	I/O4	NC	A 16	I/O ₁₂	Vss
F	I/O6	I/O ₅	A 14	A 15	I/O13	VO14
G	I /O ₇	NC	A 12	A 13	WE	VO15
Н	NC	A 8	А9	A 10	A 11	NC

3624 tbl 11

SOJ Capacitance

 $(TA = +25^{\circ}C, f = 1.0MHz)$

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
Cin	Input Capacitance	VIN = 3dV	7	pF
Cı/o	I/O Capacitance	Vout = 3dV	8	pF

3624 tbl 02

48 BGA Capacitance

 $(TA = +25^{\circ}C, f = 1.0MHz)$

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	6	pF
Cvo	VO Capacitance	Vout = 3dV	7	pF

NOTE:

3624 tbl 02b

^{*}Pin 28 can either be a NC or connected to Vss

^{1.} This parameter is guaranteed by device characterization, but not production tested.

Absolute Maximum Ratings(1)

Symbol	Rating	Value	Unit
VDD	Supply Voltage Relative to Vss	-0.5 to +4.6	V
VIN, VOUT	Terminal Voltage Relative to Vss	-0.5 to VDD+0.5	V
TBIAS	Temperature Under Bias	-55 to +125	°C
Tstg	Storage Temperature	-55 to +125	°C
Рт	Power Dissipation	1	W
Іоит	DC Output Current	50	mA

3624 tbl 04

NOTE

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Recommended Operating Temperature and Supply Voltage

Grade	Temperature	Vss	V DD
Commercial	0°C to +70°C	0V	See Below
Industrial	-40°C to +85°C	0V	See Below

3624 tbl 05

Recommended DC Operating Conditions

Symbol	Parameter	Parameter Min. Typ.		Max.	Unit
VDD	Supply Voltage	3.0	3.3	3.6	V
Vss	Ground	0	0	0	V
ViH	Input High Voltage	2.0		VDD+0.3 ⁽¹⁾	٧
VIL	Input Low Voltage	-0.3 ⁽²⁾		0.8	٧

NOTES:

- 1. VIH (max.) = VDD+2V for pulse width less than 5ns, once per cycle.
- 2. VIL (min.) = -2V for pulse width less than 5ns, once per cycle.

Truth Table(1)

<u>cs</u>	ŌĒ	WE	BLE	BHE	I/O ₀ -I/O ₇	I/O8-I/O15	Function
Н	Х	Х	Х	Х	High-Z	High-Z	Deselected - Standby
L	L	Н	L	Н	DATAout	High-Z	Low Byte Read
L	L	Н	Н	L	High-Z	DATAout	High Byte Read
L	L	Н	L	L	DATAout	DATAout	Word Read
L	Х	L	L	L	DATAIN	DATAIN	Word Write
L	Х	L	L	Н	DATAIN	High-Z	Low Byte Write
L	Х	L	Н	L	High-Z	DATAIN	High Byte Write
L	Н	Н	Х	Х	High-Z	High-Z	Outputs Disabled
L	Х	Х	Н	Н	High-Z	High-Z	Outputs Disabled

NOTF:

1. $H = V_{IH}$, $L = V_{IL}$, X = Don't care.

3624 tbl 03

DC Electrical Characteristics

(VDD = Min. to Max., Commercial and Industrial Temperature Ranges)

		IDT71V416		IV416	
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Iu	Input Leakage Current	Vcc = Max., Vin = Vss to Vdd	_	5	μA
ILO	Output Leakage Current	VDD = Max., $\overline{\text{CS}}$ = VIH, VOUT = VSS to VDD		5	μΑ
Vol	Output Low Voltage	IOL = 8mA, VDD = Min.	-	0.4	V
Vон	Output High Voltage	Iон = -4mA, V _{DD} = Min.	2.4		V

3624 tbl 07

3624 tbl 08

DC Electrical Characteristics(1, 2, 3)

(VDD = Min. to Max., VLC = 0.2V, VHC = VDD - 0.2V)

			71V41	6S/L10	71V41	6S/L12	71V41	6S/L15	
Symbol	Parameter		Com'l.	Ind. ⁽⁵⁾	Com'l.	Ind.	Com'l.	Ind.	Unit
Icc	$\frac{\text{Dynamic Operating Current}}{\text{CS}} \leq \text{VLc, Outputs Open, VDD} = \text{Max., f} = \text{fmax}^{(4)}$	S	200	200	180	180	170	170	mA
		L	180	-	170	170	160	160	
Isb	Dynamic Standby Power Supply Current		70	70	60	60	50	50	mA
	$\overline{CS} \ge VHC$, Outputs Open, $VDD = Max$., $f = fMax^{(4)}$	L	50	_	45	45	40	40	
ISB1	ISB1 Full Standby Power Supply Current (static)		20	20	20	20	20	20	mA
	$\overline{\text{CS}} \ge \text{VHC}$, Outputs Open, $\text{VDD} = \text{Max.}$, $f = 0^{(4)}$	L	10	_	10	10	10	10	

NOTES:

- 1. All values are maximum guaranteed values.
- 2. All inputs switch between 0.2V (Low) and VDD -0.2V (High).
- 3. Power specifications are preliminary.
- 4. fMAX = 1/trc (all address inputs are cycling at fmax); f = 0 means no address input lines are changing.
- 5. Standard power 10ns (S10) speed grade only.

AC Test Loads

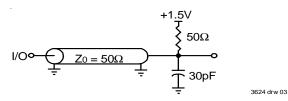


Figure 1. AC Test Load

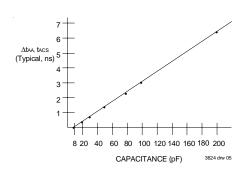
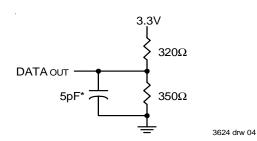


Figure 3. Output Capacitive Derating



*Including jig and scope capacitance.

Figure 2. AC Test Load (for tclz, tolz, tchz, tohz, tow, and twhz)

AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	1.5ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	Figures 1,2 and 3

3624 tbl 09

AC Electrical Characteristics

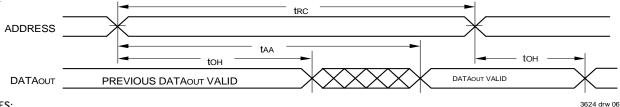
(VDD = Min. to Max., Commercial and Industrial Temperature Ranges)

		71V416	S/L10 ⁽²⁾	71V416S/L12		71V416S/L15		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYCLE								
trc	Read Cycle Time	10		12	_	15	_	ns
taa	Address Access Time	_	10	_	12	_	15	ns
tacs	Chip Select Access Time	_	10	_	12	_	15	ns
talz(1)	Chip Select Low to Output in Low-Z	4	_	4	_	4	_	ns
tcHZ ⁽¹⁾	Chip Select High to Output in High-Z	_	5	_	6	_	7	ns
toe	Output Enable Low to Output Valid	_	5	_	6	_	7	ns
toLz ⁽¹⁾	Output Enable Low to Output in Low-Z	0	_	0		0	_	ns
tohz ⁽¹⁾	Output Enable High to Output in High-Z	_	5	_	6	_	7	ns
toн	Output Hold from Address Change	4	_	4		4	_	ns
tBE	Byte Enable Low to Output Valid	_	5		6		7	ns
tBLZ ⁽¹⁾	Byte Enable Low to Output in Low-Z	0	_	0		0	_	ns
tвнz ⁽¹⁾	Byte Enable High to Output in High-Z	_	5	_	6		7	ns
WRITE CYCL	E							
twc	Write Cycle Time	10		12		15	_	ns
taw	Address Valid to End of Write	8		8		10	_	ns
tcw	Chip Select Low to End of Write	8	_	8		10	_	ns
tвw	Byte Enable Low to End of Write	8	_	8		10	_	ns
tas	Address Set-up Time	0	_	0		0	_	ns
twr	Address Hold from End of Write	0		0		0	_	ns
twp	Write Pulse Width	8		8		10	_	ns
tow	Data Valid to End of Write	5		6	_	7	_	ns
tdh	Data Hold Time	0	_	0	_	0	_	ns
tow ⁽¹⁾	Write Enable High to Output in Low-Z	3	_	3	_	3	_	ns
twHZ ⁽¹⁾	Write Enable Low to Output in High-Z	_	6		7		7	ns

3624 tbl 10

- 1. This parameter is guaranteed with the AC Load (Figure 2) by device characterization, but is not production tested.
- 2. Low power 10ns (L10) speed 0°C to +70°C temperature range only.

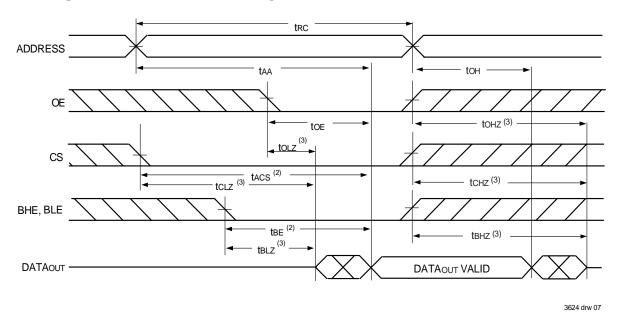
Timing Waveform of Read Cycle No. 1(1,2,3)



NOTES:

- WE is HIGH for Read Cycle.
 Device is continuously selected, S is LOW.
- 3. $\overline{\text{OE}}$, $\overline{\text{BHE}}$, and $\overline{\text{BLE}}$ are LOW.

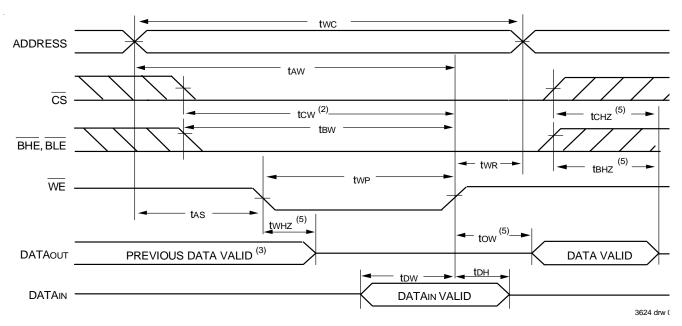
Timing Waveform of Read Cycle No. 2⁽¹⁾



NOTES:

- 1. $\overline{\text{WE}}$ is HIGH for Read Cycle.
- 2. Address must be valid prior to or coincident with the later of $\overline{\text{CS}}$, $\overline{\text{BHE}}$, or $\overline{\text{BLE}}$ transition LOW; otherwise tax is the limiting parameter.
- 3. Transition is measured ±200mV from steady state.

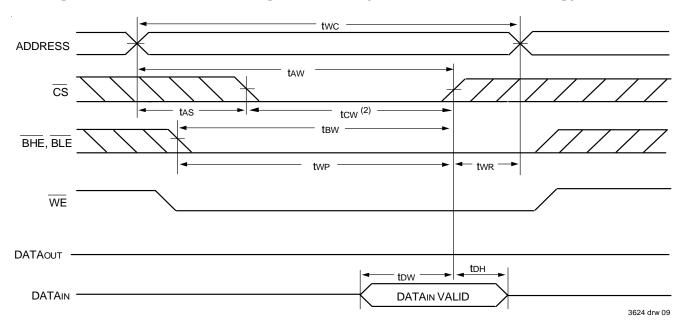
Timing Waveform of Write Cycle No. 1 (WE Controlled Timing)(1,2,4)



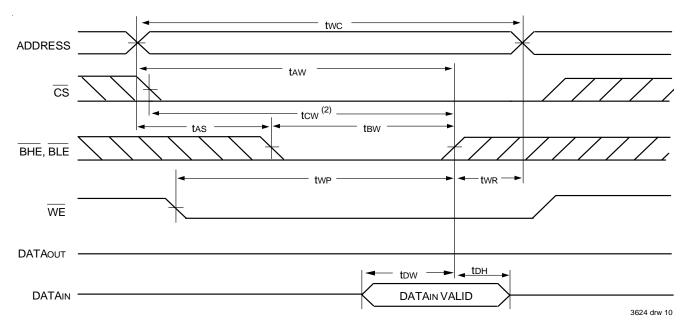
NOTES:

- 1. A write occurs during the overlap of a LOW \overline{CS} , LOW \overline{BHE} or \overline{BLE} , and a LOW \overline{WE} .
- OE is continuously HIGH. If during a WE controlled write cycle OE is LOW, twp must be greater than or equal to twHz + tow to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If OE is HIGH during a WE controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified twp.
- 3. During this period, I/O pins are in the output state, and input signals must not be applied.
- 4. If the $\overline{\text{CS}}$ LOW or $\overline{\text{BHE}}$ and $\overline{\text{BLE}}$ LOW transition occurs simultaneously with or after the $\overline{\text{WE}}$ LOW transition, the outputs remain in a high-impedance state.
- 5. Transition is measured ±200mV from steady state.

Timing Waveform of Write Cycle No. 2 (CS Controlled Timing)(1,3)



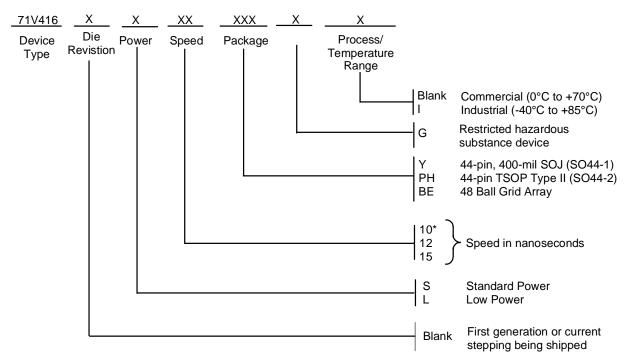
Timing Waveform of Write Cycle No. 3 (BHE, BLE Controlled Timing)(1,3)



NOTES:

- 1. A write occurs during the overlap of a LOW $\overline{\text{CS}}$, LOW $\overline{\text{BHE}}$ or $\overline{\text{BLE}}$, and a LOW $\overline{\text{WE}}$.
- 2. During this period, I/O pins are in the output state, and input signals must not be applied.
- 3. If the CS LOW or BHE and BLE LOW transition occurs simultaneously with or after the WE LOW transition, the outputs remain in a high-impedance state.

Ordering Information



^{*} Commercial only for low power 10ns (L10) speed grade.

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Datasheet Document History

08/5/99		Updated to new format
	Pg 6	Revised footnote for tCW on Write Cycle No. 1 diagram
08/31/99	Pg. 1–9	Added Industrial temperature range offering
	Pg. 9	Added Datasheet Document History
03/24/00	Pg. 6	Changed note to Write cycle No. 1 according to footnotes
08/10/00		Add 48 ball grid array package offering
	Pg. 1	Correct TTL to LVTTL
09/11/02	Pg. 2	Updated TBD information for the 48 BGA Capacitance table
11/26/02	Pg. 8	Added "Die Revision" to ordering information
07/31/03	Pg. 8	Updated note, L10 speed grade commercial temperature only and updated die stepping from YF to Y.
10/13/03	Pg. 8	Updated ordering information. Refer to 71V416YS and 71V416YL datasheet for latest generation die step.
01/30/04	Pg. 8	Added "Restricted hazardous substance device" to ordering information.
10/16/08	Pg. 8	Removed "IDT" from orderable pat number.



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